

## Freeform Search

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US Pre-Grant Publication Full-Text Database  
JPO Abstracts Database  
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Derwent World Patents Index  
IBM Technical Disclosure Bulletins

**Term:** 15 and dissipat\$

**Display:** 10 **Documents in Display Format:** CIT **Starting with Number** 1

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Today's Date: 7/20/2001

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	15 and dissipat\$	27	<u>L6</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(bond near (tool or tip or capillary)) and (metal or conduct) and (ceramic or semiconducting or insulating or insulative or insulator or dielectric)	210	<u>L5</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	11 and (bond near (tool or tip or capillary))	0	<u>L4</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	12 and (bond near (tool or tip or capillary))	0	<u>L3</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	11 and (semiconductor or ceramic)	69	<u>L2</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(electric or electronic) near (dissipate or dissipative)	269	<u>L1</u>

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## Search Results -

Terms	Documents
bond (tool or tip or capillary or foot) and (semiconduct or semiconductor) and (titanium and carbide and nitride)	5

Database: 
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Refine Search: 
 bond (tool or tip or capillary or foot)  
 and (semiconduct or semiconductor) and  
 (titanium and carbide and nitride)
 
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## Search History

**Today's Date:** 7/20/2001

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	bond (tool or tip or capillary or foot) and (semiconduct or semiconductor) and (titanium and carbide and nitride)	5	<u>L2</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	bond (tool or tip or capillary or foot) and (dissipate or dissipative)	12	<u>L1</u>